WinWay *Your Trusted Partner in Semiconductor Testing*

TWSE:6515

Investor Presentation

2026.05.26

Safe Harbor Notice

This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

Founded

2001.4 .10

Capital Stock

NTD 360,416,420

Employees

1408

Chairman & CEO

Mark Wang

Business Operation

Design, manufacture, sale and service of test interface products

Registered Address

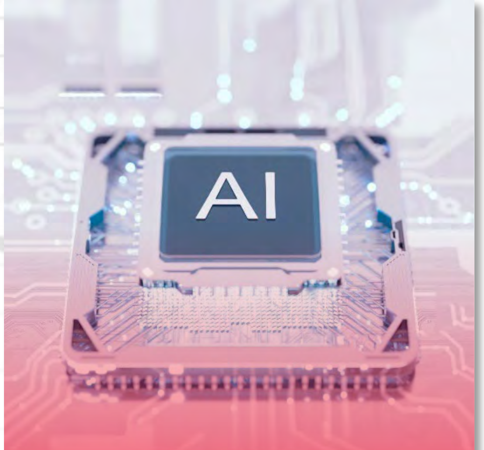
No.68, Chuangyi S. Rd, Nanzi Dist.
Kaohsiung City, Taiwan

Kaohsiung Headquarter

USA Branch Office

Hsinchu Branch Office

Company Vision



Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.

Quality

We exceed customers’ quality requirements by offering cost-effective total solutions and on-time delivery worldwide.

Service

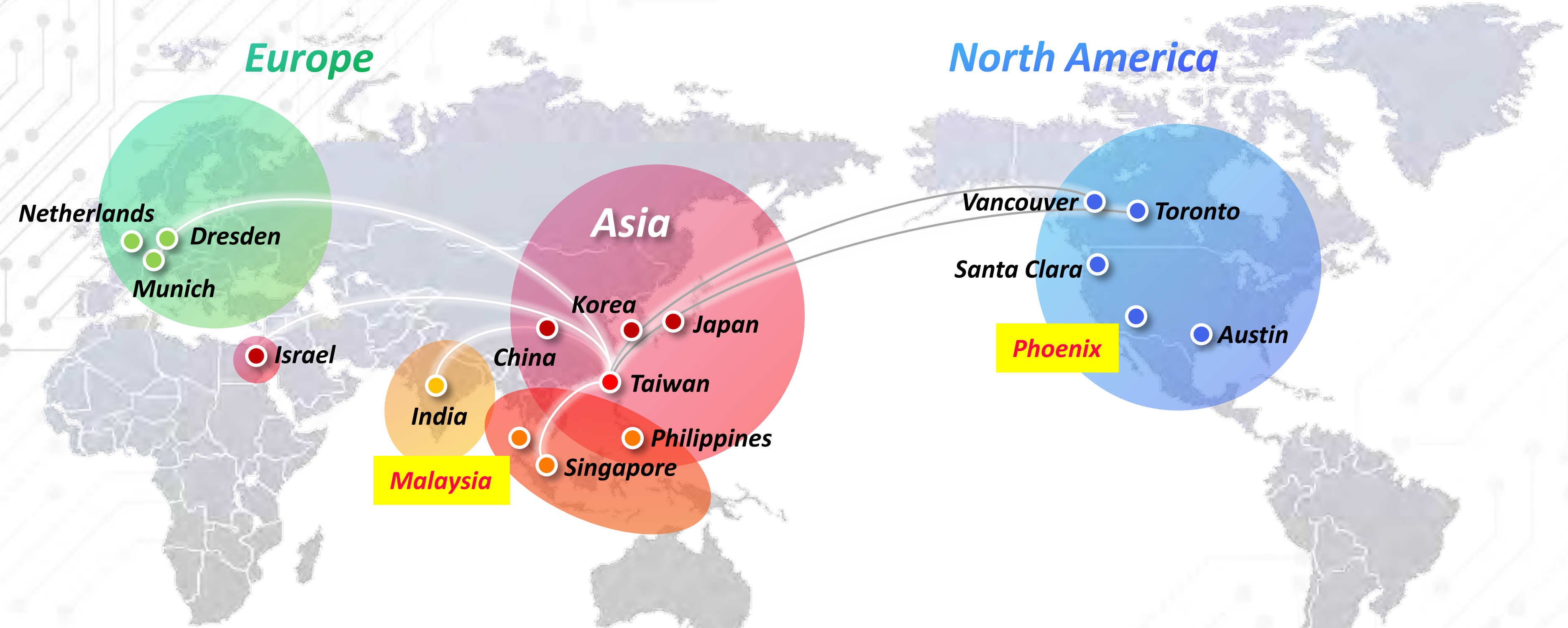
We strive to become the world’s leading professional testing service provider in all phases of IC testing.

Agenda

- Global Presence
- Industry Trend
- Financial Performance
- R&D Innovation

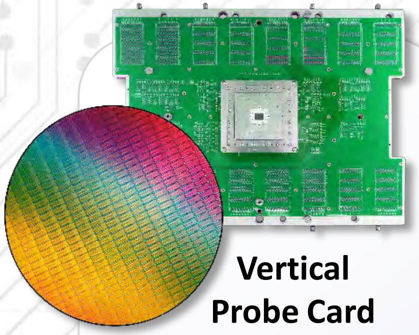
Global Presence

Global Service & Support Network

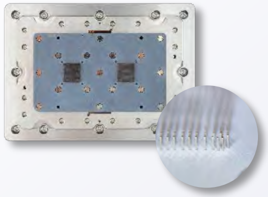


KH Spring Probe	KH Plant	Hsinchu Plant	Suzhou Plant	Renwu Plant
Spring Probe for Socket	Coaxial Socket HyperSocket™	Vertical Probe Card MEMS Probe Card	Coaxial Socket	Coaxial Socket

Your Trusted Partner in Semiconductor Testing

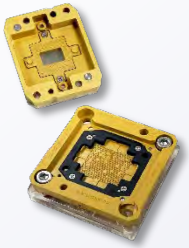


Vertical Probe Card

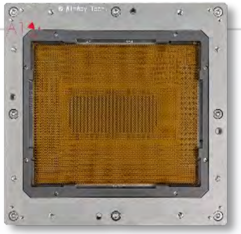


MEMS Probe Card

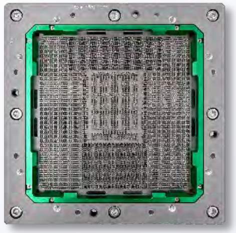
Coaxial Socket



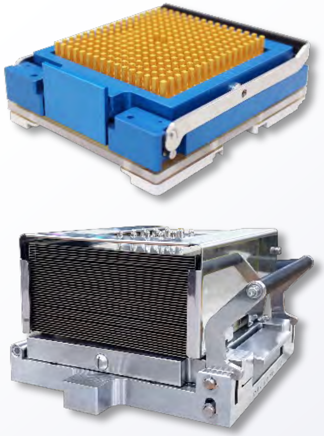
PoP Socket



HyperSocket™



Coaxial Socket



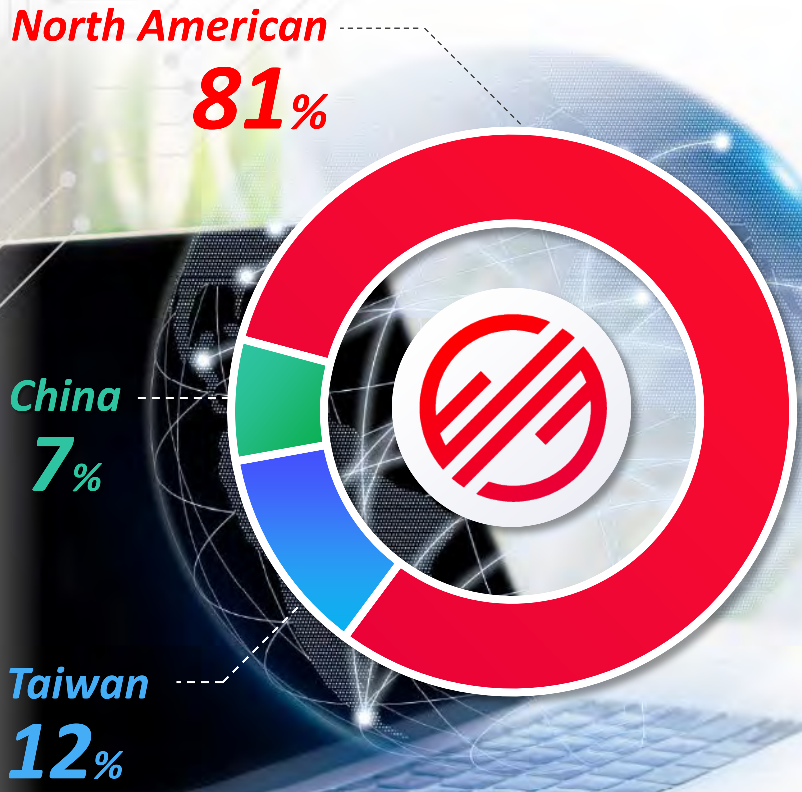
Production Burn-in Socket

Wafer Sort → Final Test → SLT & SFT → Functional Burn-in

DFT Design For Testing **DFM** Design For Manufacturing

Worldwide Customer

First 4 Months of 2026



Top10 Customers

90%

- AI
- CPU
- HPC
- GPU
- ASIC
- AP

Active Customers

200+

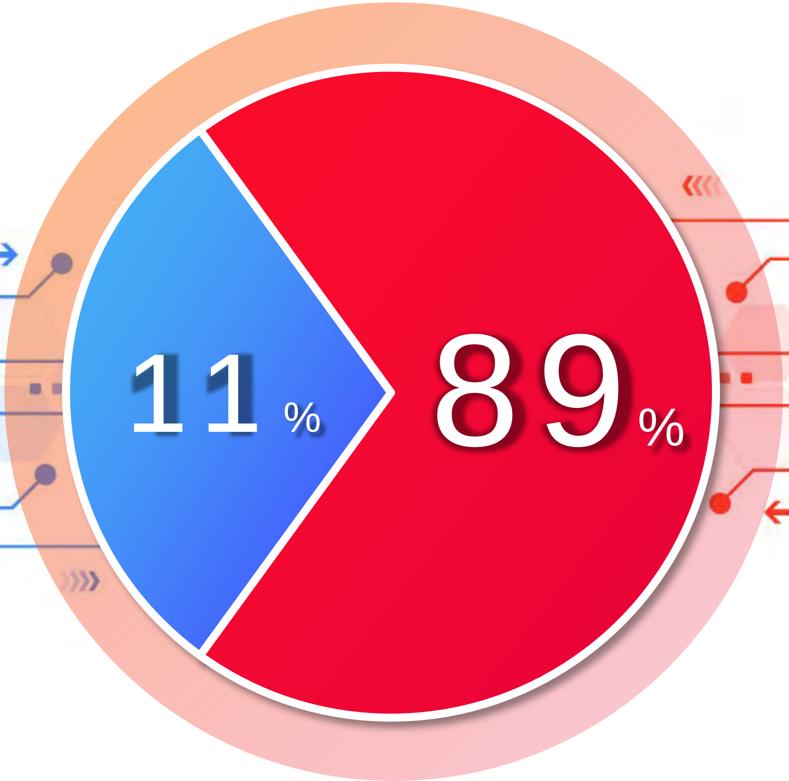
- IC Design
- ASIC
- CSP
- OSAT
- Foundry
- IDM

Bolstered by Advanced Technology

First 4 Months of 2026

Mature Node

- Automotive
- Networking
- IoT
- DTV & STB
- NAND Flash



Advanced Node

7nm (or equivalent node) and below

- AI
- HPC
- GPU
- CPU
- Smart Phone

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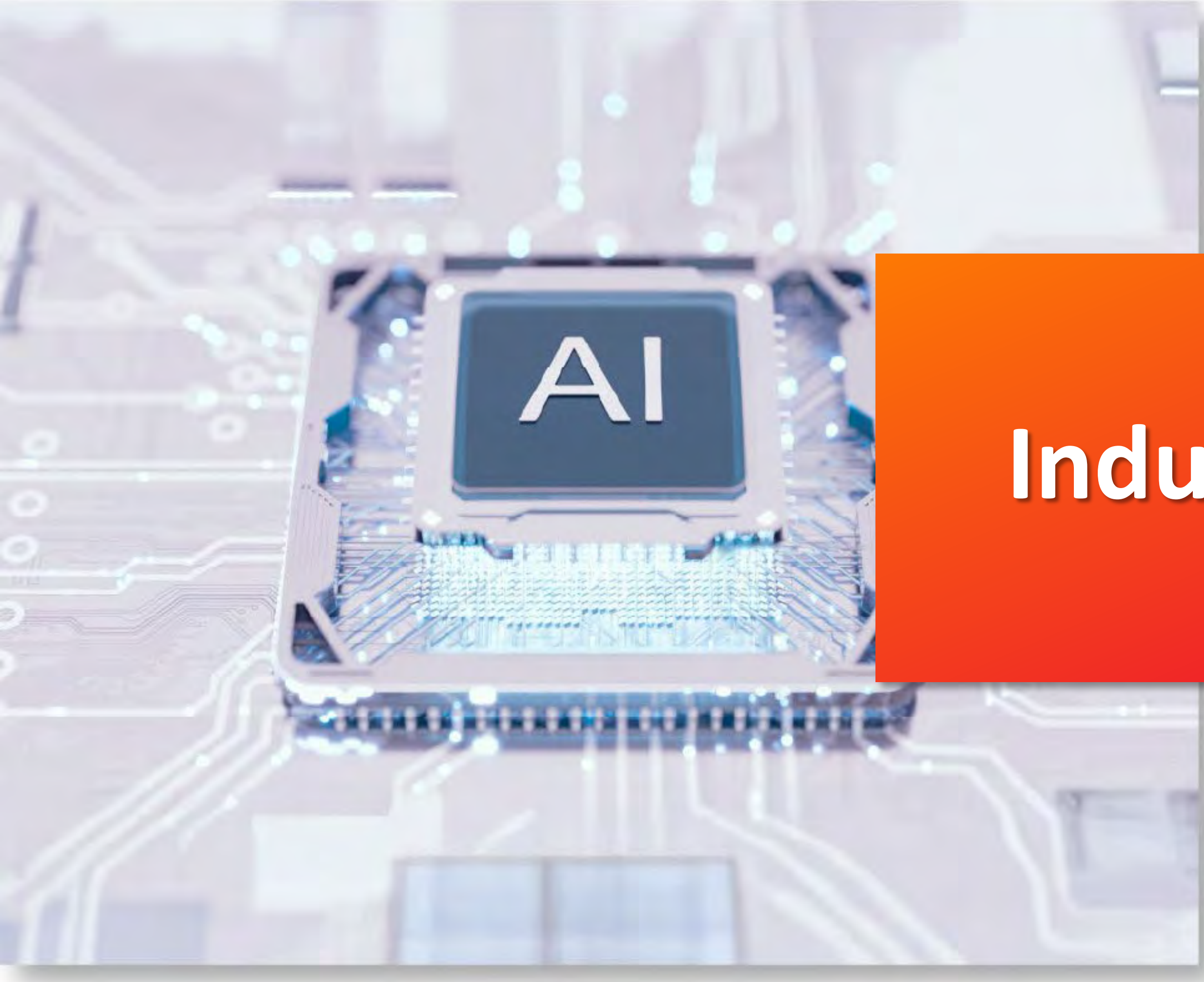
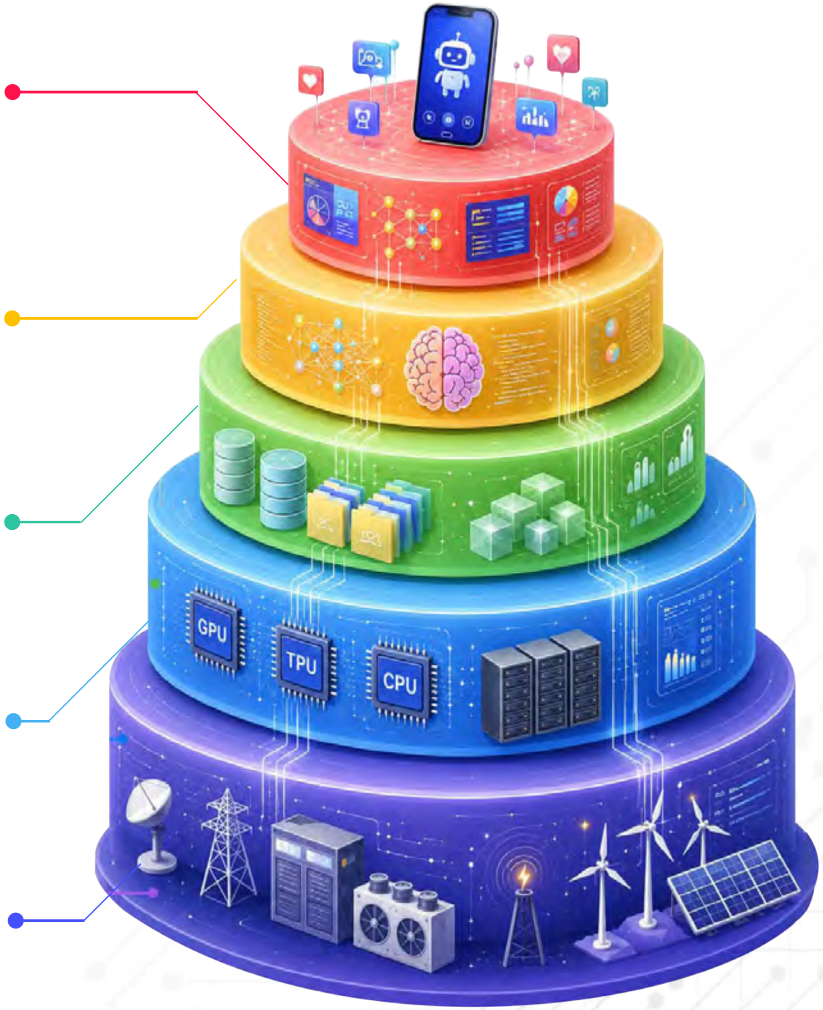


Industry Trend

AI Advances the Value Chain of Tomorrow



Applications

- AI Agent
- LLM / Gen AI
- AI PC
- Humanoid Robot
- Smart Factory
- Self-driving car
- AR/VR
- Digital Twins
- Smart City

Models

- AI Framework
- Foundation Model
- MLOps / Platform
- AI Training Platform

Infrastructure

- AI Factory
- Liquid Cooling
- Hyperscale Datacenter
- Optical Network

Chips

- GPU
- XPU
- AI ASIC
- CPU
- CoWoS / SoIC
- HBM
- Chiplet
- CPO / CPC

Energy

- Power Delivery
- Green Energy
- Electric power

Source : NVIDIA

WinWay

Driving Force for AI

Agentic AI

AI
PC & Phone

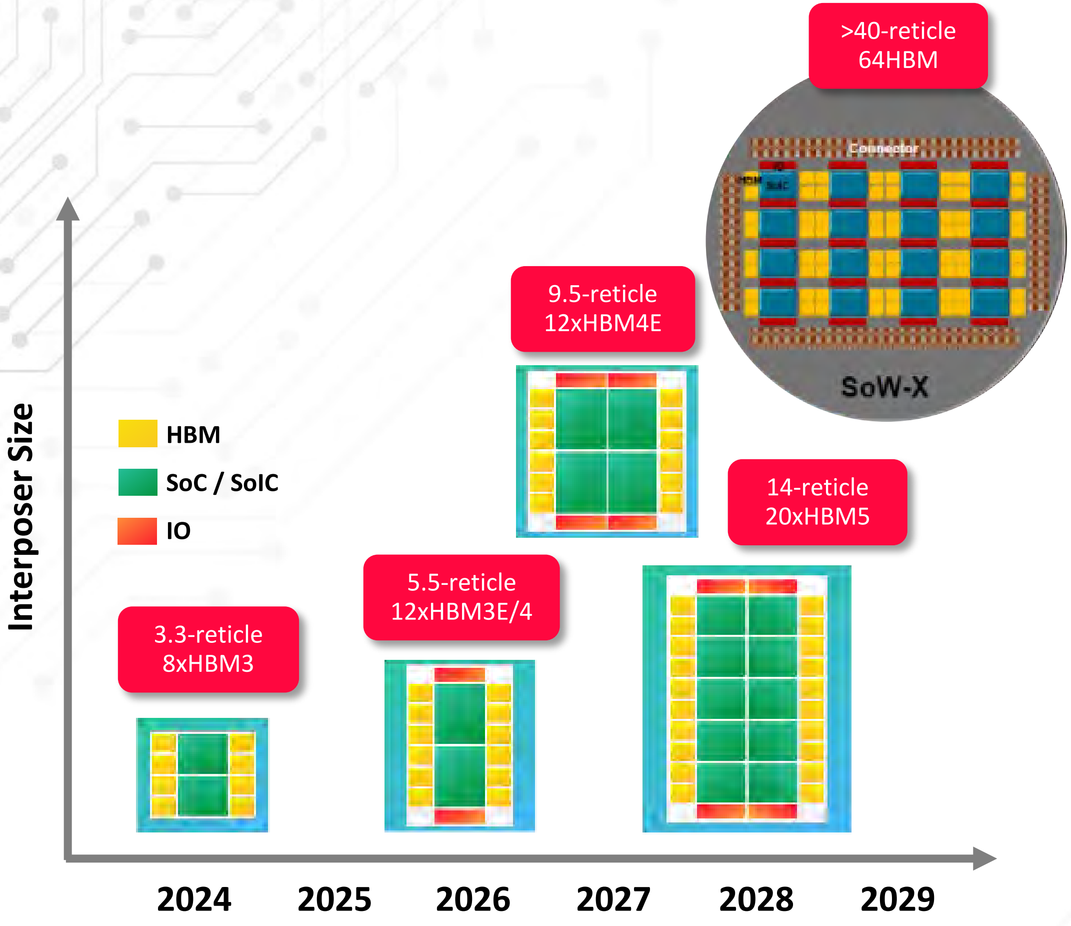
High Speed
Networking

Collaborative
Robots

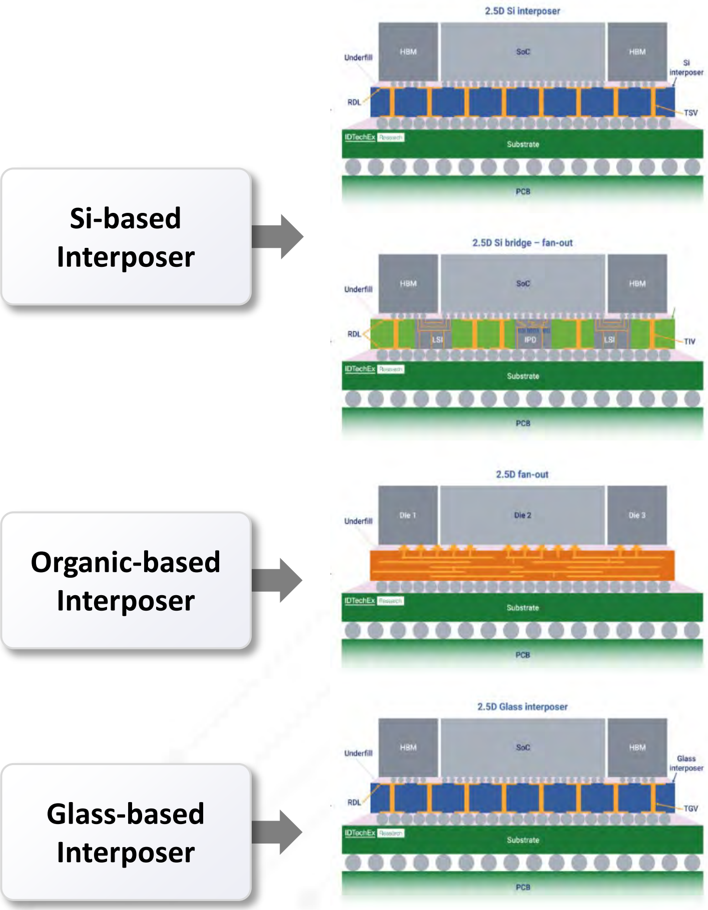
Edge
Computing

Data Center

Performance Breakthrough:
Evolution of Advanced Packaging



Source : TSMC



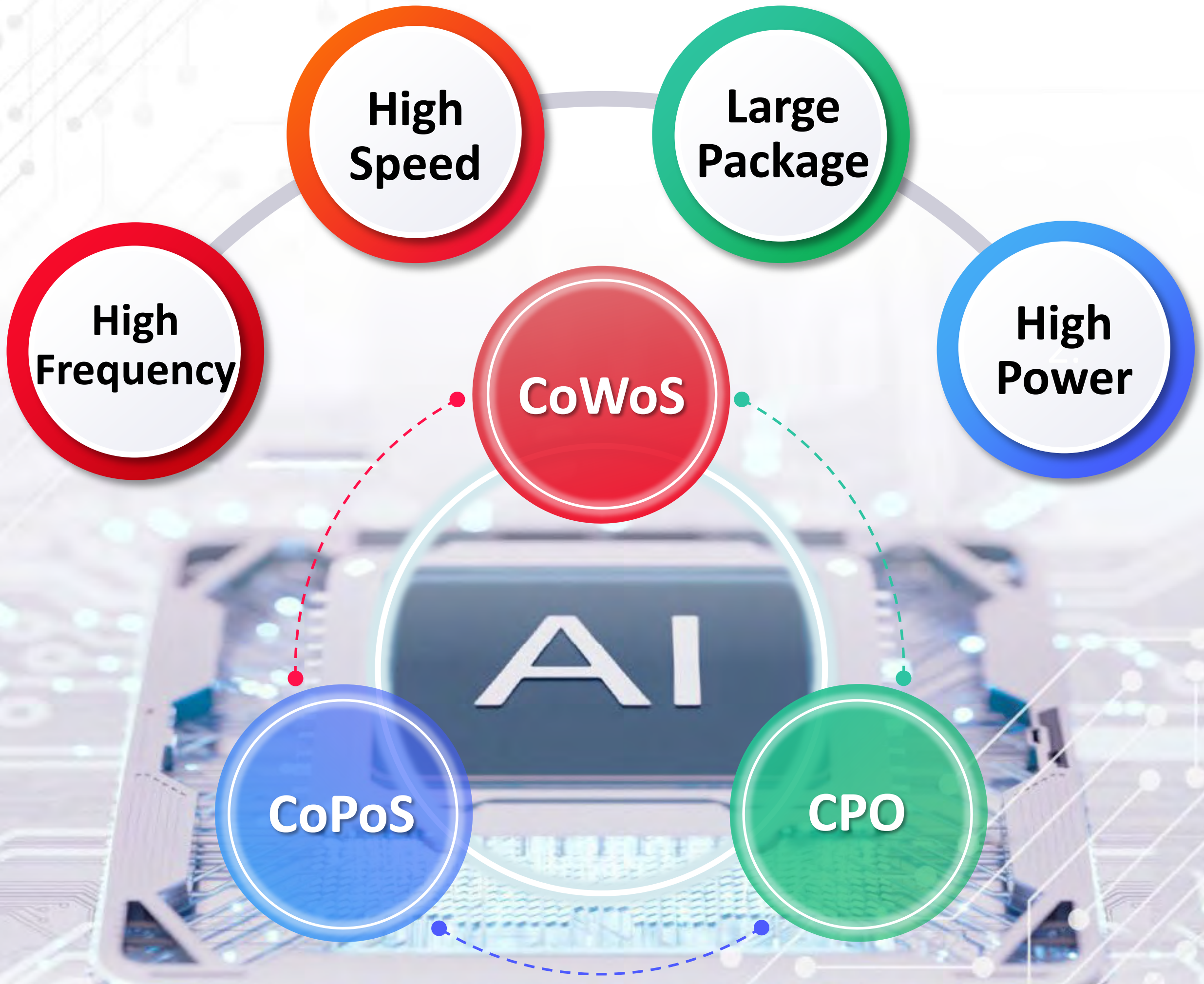
Si-based Interposer

Organic-based Interposer

Glass-based Interposer

Source : IDTechEx Research

High Performance Testing Driven by Advanced Packaging



High Frequency

High Speed

Large Package

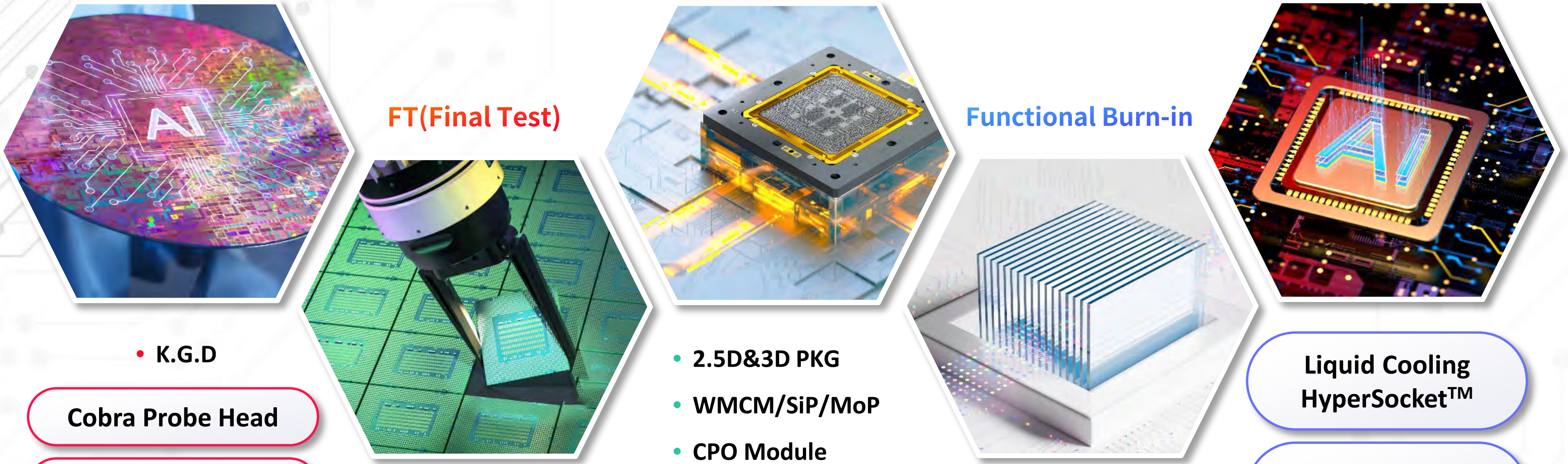
High Power

CoWoS

CoPoS

CPO

Opportunities for Semi Test Interface



Wafer Sort (CP - Circuit Probe)

- K.G.D

Cobra Probe Head

MEMS Probe Head

FT(Final Test)

- CPO/CPC substrate
- Optical Engine
- WMCM/SiP/MoP

Coaxial Socket

PoP Socket

SLT (System Level Test) , SFT

- 2.5D&3D PKG
- WMCM/SiP/MoP
- CPO Module

HyperSocket™

Coaxial Socket

Functional Burn-in

Production Burn-in

Functional Burn-in

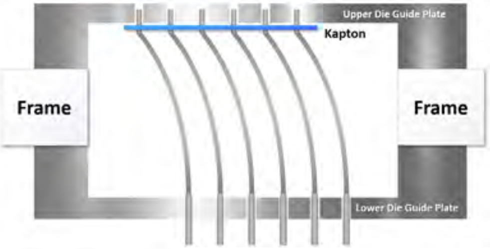
(Thermal System)

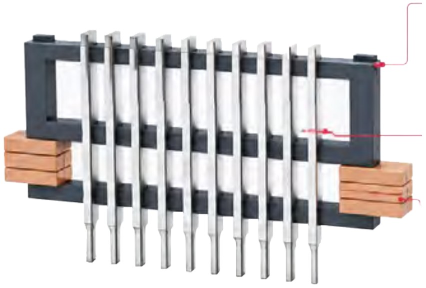
Liquid Cooling HyperSocket™

Active Thermal Controller

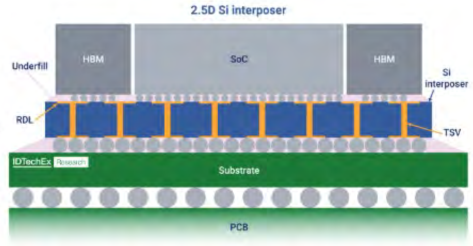
Greater Importance on Chip Probing

At Speed Test and K.G.D



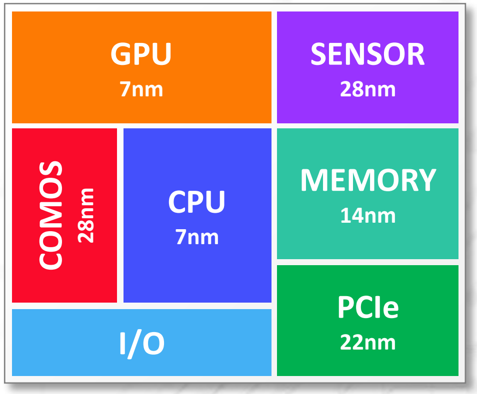


	Cobra	*MEMS*
Pin Count	Less, limited to probe force design	★ **Higher (More flexible to design)**
CCC(A)	2.2 @ 4mil probe diameter	★ **2.2 @ 3mil probe diameter**
High Speed	32G	★ **112G**
Force(g)	2~25	★ **1.5 ~ 4.5**
Pitch (um)	80~200	★ **40~200**
Operating Temp.	- 50℃ to 150℃	★ **- 50℃ to 175℃**



Source : IDTechEx Research

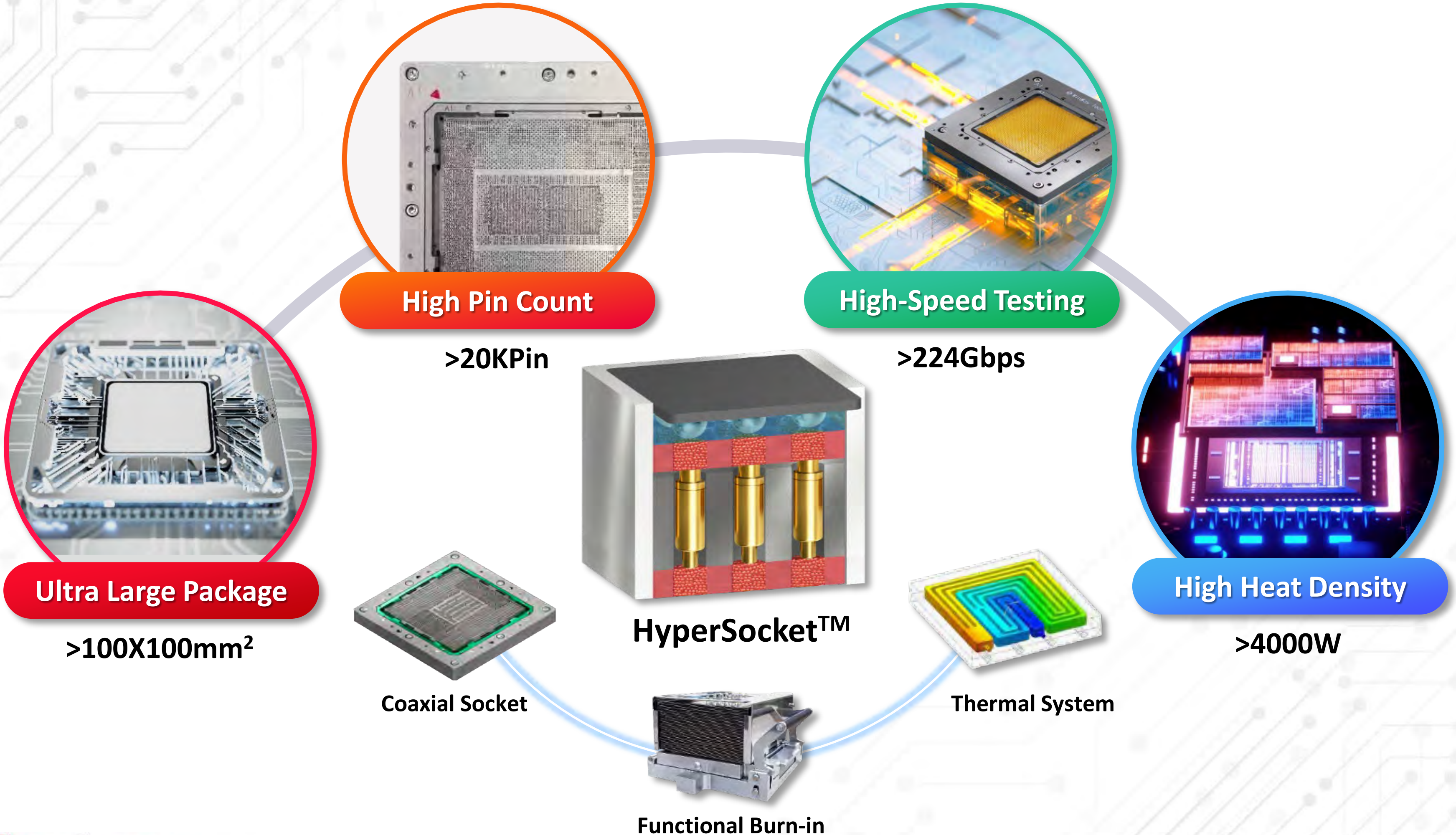
Chiplet **Multiple Probe Card Demand**



Source : Trend Force

Accelerated SLT Demand Driven by AI

Comprehensive solution for all test insertions



Ultra Large Package

>100X100mm^2

High Pin Count

>20KPin

High-Speed Testing

>224Gbps

High Heat Density

>4000W

HyperSocket™

Coaxial Socket

Thermal System

Functional Burn-in

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Financial Performance

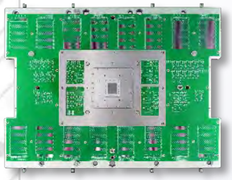
Statements of Comprehensive Income

2025 Dividend (NTD) **50**

(NTD MILLION)	1Q26	4Q25	1Q25	1Q26 Over 4Q25	1Q26 Over 1Q25
Revenue	2,980	2,234	2,297	+33%	+30%
Gross Margin	43%	42%	49%	+1ppts	-6ppts
Operating Expenses	505	457	393	+11%	+29%
Operating Margin	26%	21%	32%	+5ppts	-6ppts
Net Income	699	483	613	+45%	+14%
Net Margin	24%	22%	27%	+2ppts	-3ppts
EPS (NTD)	19.54	13.53	17.21	+44%	+14%

Revenue by Product Mix

First 4 Months of 2026



Probe Card

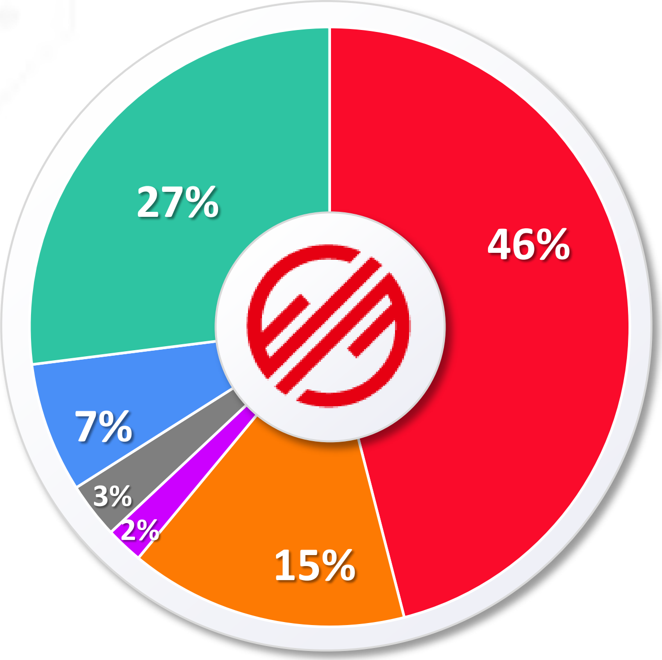
27 %

Contact Element

7 %

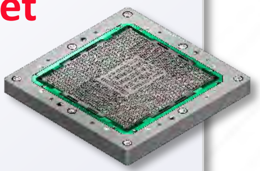
Others

3 %



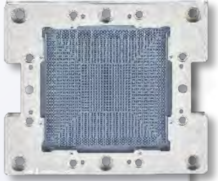
Coaxial Socket

46 %



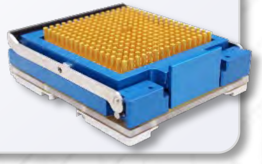
PoP & Plastic Socket

15 %



Burn-in Socket

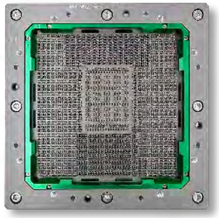
2 %



Revenue by End Market

First 4 Months of 2026

HyperSocket™



Coaxial Socket

HPC & AI

68 %

Networking
Auto / Others

22 %

Plastic Socket

Smart Phone

8 %

POP Plastic Socket

PC & Gaming

2 %

POP Plastic Socket

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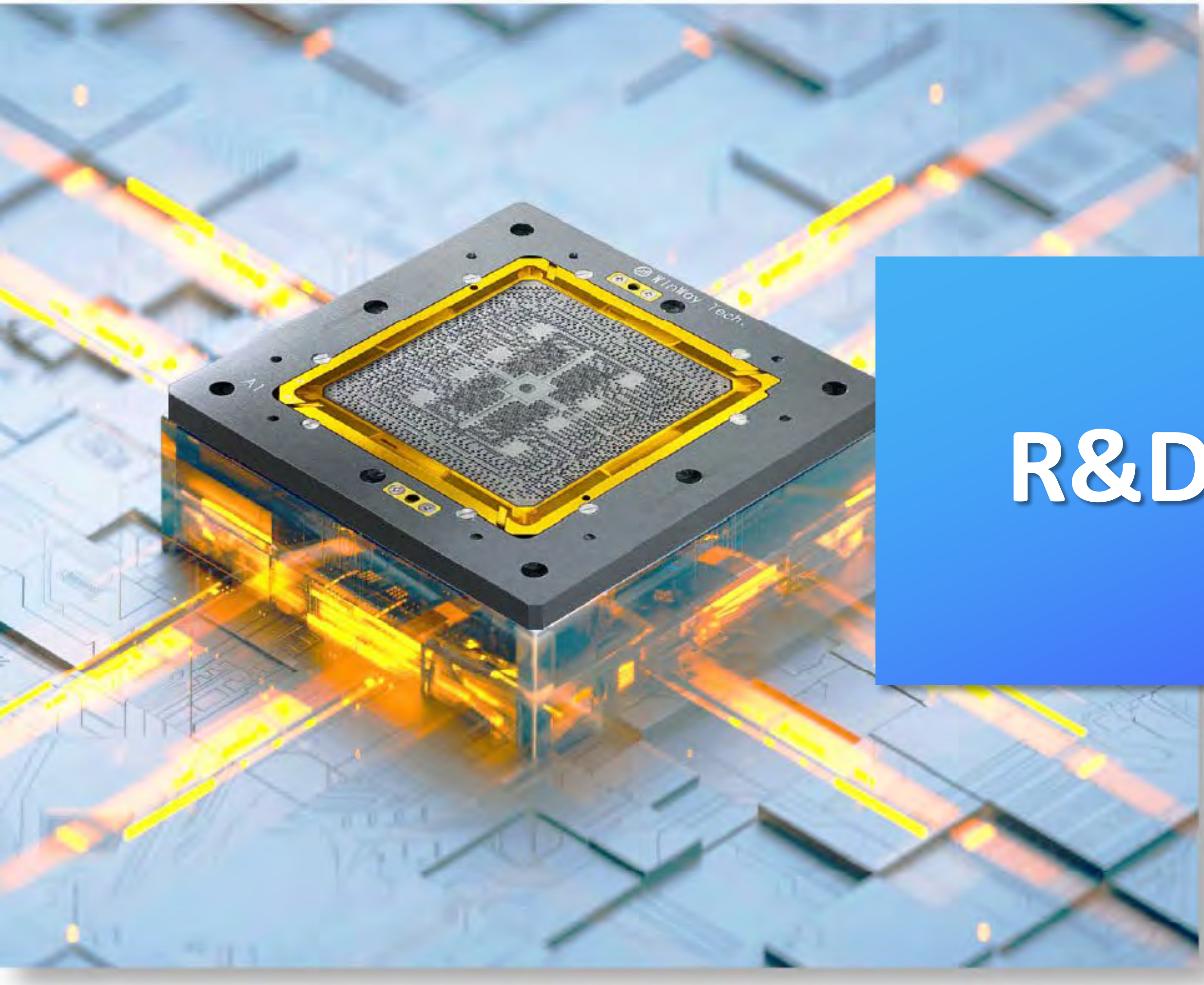


R&D Innovation

Innovative Semiconductor Test Interface Solution

HyperSocket^{TM}-Dual Film

Patent NO.

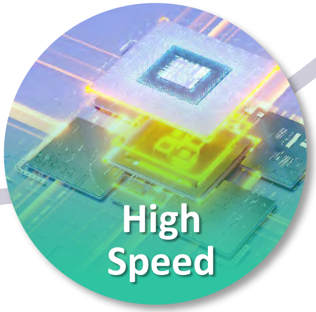
TWI862047
TWI884802
TWI862191
TWI901161
TWI922268
TWI923382
CN220584352

Patent Pending

USA
Malaysia

- Larger contact area
- Improved heat dissipation
- Enhanced test stability

- Various current pathways
- Mitigating temperature rise



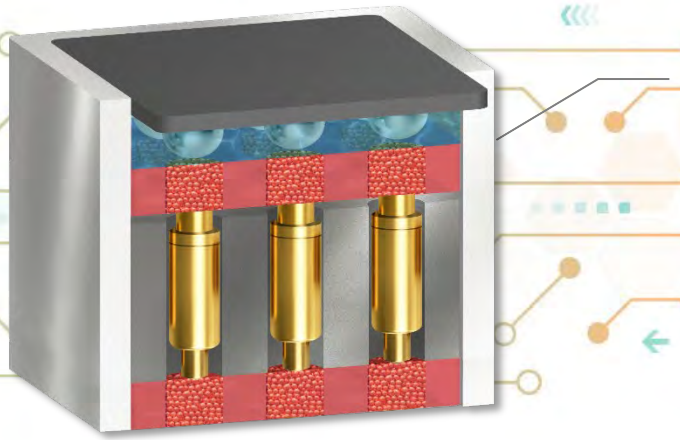
- Full metal shielding, short-loop design
- Test speed above 224Gbps

- Zero Pre-load design
- Reduced maintenance cost

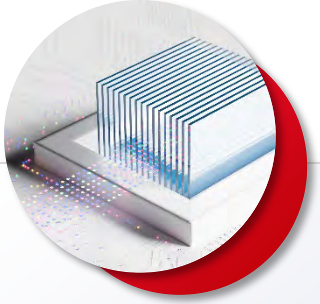
WinWay

Innovative Semiconductor Test Interface Solution

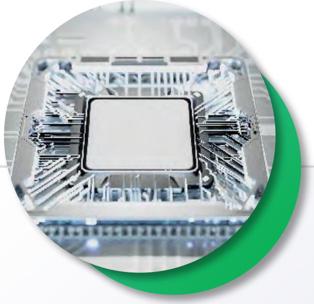
Liquid Cooling Socket



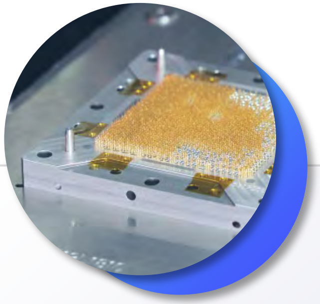
Patent NO.
TWI901181
US12625162



Extraordinary heat dissipation



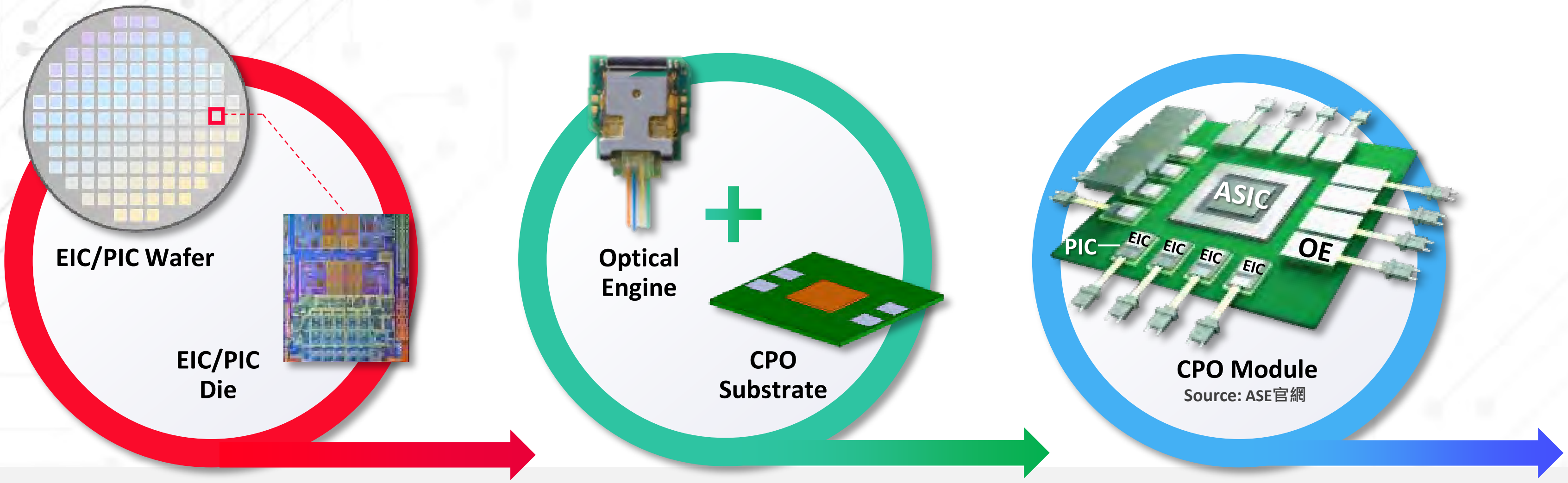
Improved Test Stability For Advanced Packaging



Extend Spring Probe Lifespan

WinWay

Co-Packaged Optics Test Solution



EIC/PIC Wafer

EIC/PIC Die

Optical Engine

\+

CPO Substrate

CPO Module

Source: ASE官網

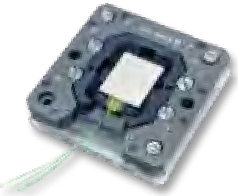
Wafer Level ➞ Die Level

Package Level

Module Level

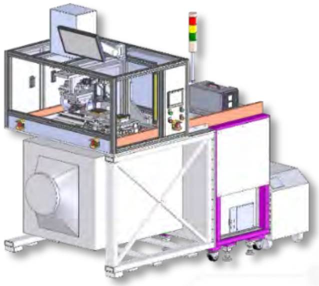
WLCSP Probe Head

(PIC & EIC Wafer test)

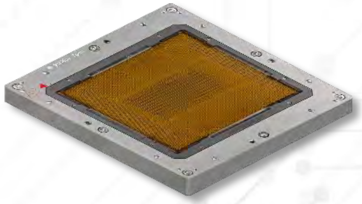


Optical and Electrical Test Socket

(Optical Engine)



Double Sided Probing System



HyperSocket™

High Power Thermal Solution

E-Flux6.0 3500W Liquid Cooling System

2026 2028 2030

~2,500W ~6,000W ~8,000W

Accelerating Expansion
Spring Probe Capacity

Cost Optimization

Balanced insourcing, better cost structure

Self-Sufficiency

Autonomy of critical process technology

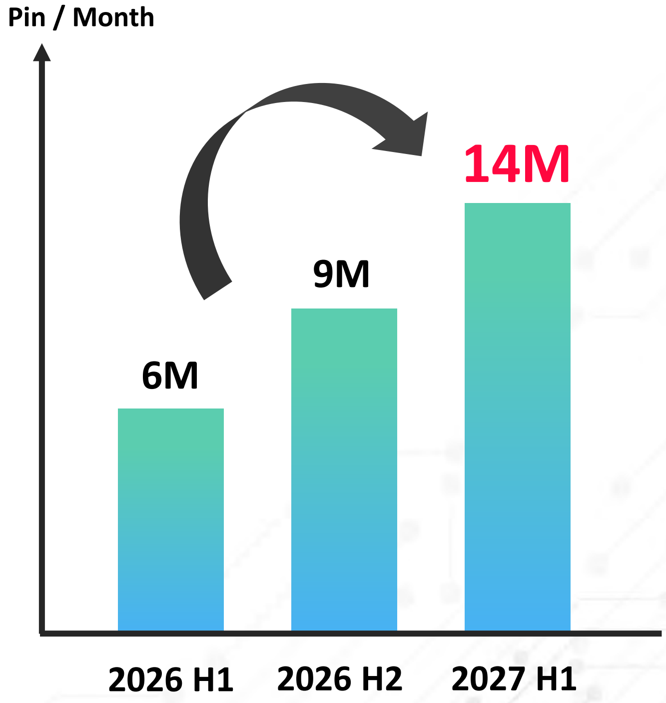
Quality Assurance

Greater customer experience

Operational Resilience

More flexible, agile lead time

WinWay Spring Probe Capacity



Accelerating Expansion
Socket Capacity

Renwu Facility I

Operational from Apr. 2026

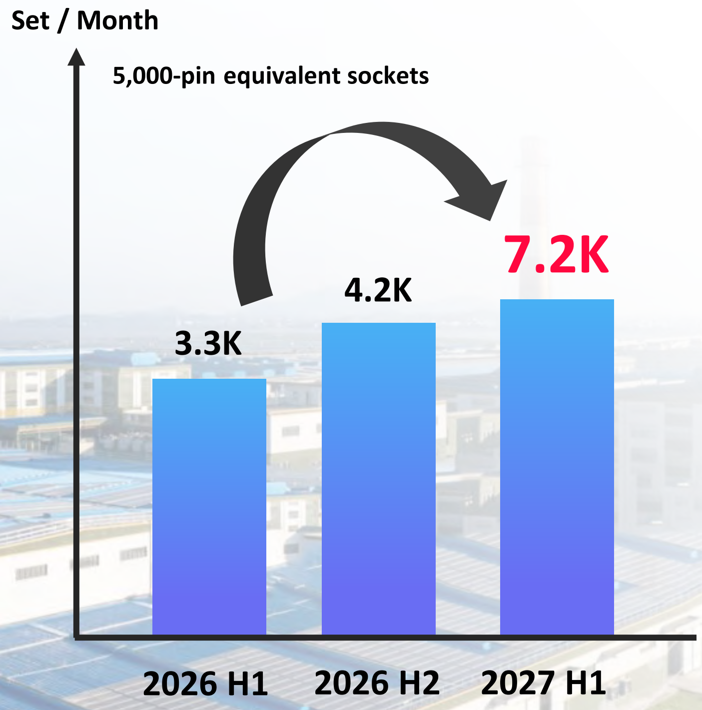
Renwu Facility II

Ground-breaking : 2026.5.29

Begin Operation : 2027 Q2

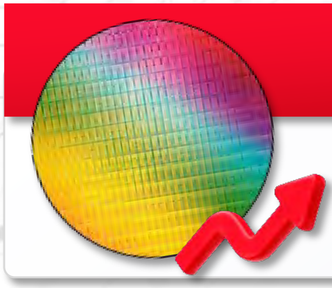
Total Area
Approx. **6300** *ping*

WinWay Socket Capacity



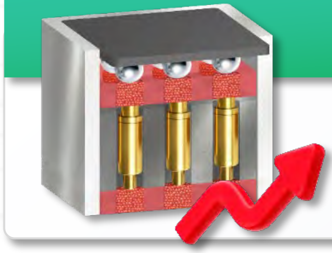
More Test Insertions

CoWoS、CoPoS、CPO



Fab and OSAT expansion drive equipment demand

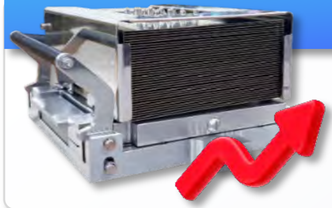
Longer and Longer Fab In-process Time



HyperSocket™ -DH

Bigger and Bigger Device Package

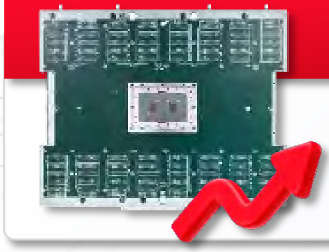
Higher and Higher Device Power Consumption



Functional Burn-In Requirement

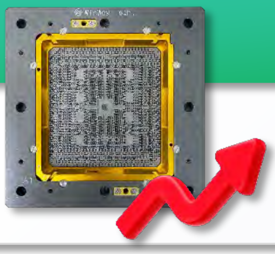
More Reliability Test Insertion

Significant Increase in Testing Time



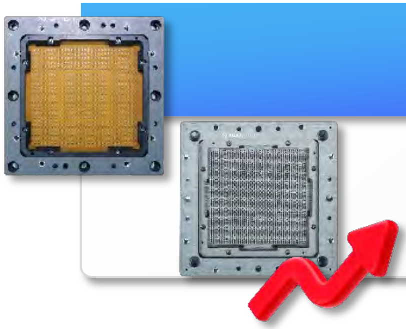
MEMS and Cobra Probe card

Longer Wafer Sort Test Time



Plastic, Coaxial and HyperSocket™

Longer FT (ATE) Test Time



Coaxial and HyperSocket™

Longer SLT Test Time

In for the Long Haul

GPU

TPU

CPU

AI ASIC

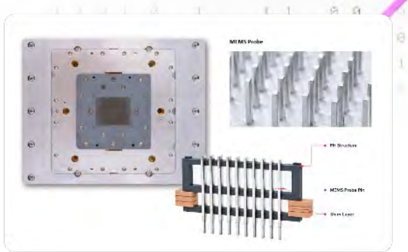
Customer Approach

Automotive

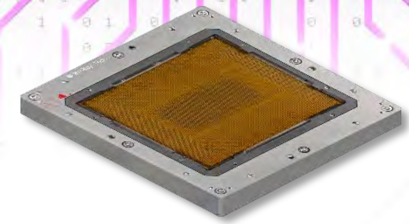
Edge Computing

High Speed Networking

Smart Phone



MEMS Probe Card



HyperSocket™

Functional Burn-in

Renwu Facility Ground-breaking Ceremony

2026.05.29

Renwu Industrial Park

No. 6, Renfa 6th Rd., Renwu Dist., Kaohsiung
City 814018, Taiwan

2026 Annual Shareholders' Meeting

2026.06.17

Zhuang Jing Auditorium

No.600,Jiachang Rd., Nanzi Dist.,
Kaohsiung City 811636 , Taiwan

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Q&A

WinWay

WinWay *Your Trusted Partner in Semiconductor Testing*

TWSE:6515

THANK YOU

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